

IN THE CLAIMS:

Please amend the claims as follows:

Claims 1-3 (Cancelled)

Claim 4 (Currently Amended): A method of manufacturing a battery pack having a vessel, a battery mounted in the vessel and a circuit board connected to the battery, comprising:

a step of forming a terminal portion in manufacturing said circuit board, said step of forming a terminal portion being to stack a base layer of copper and a plated layer of gold successively to form the terminal portion,

wherein the circuit board is a square-shaped rigid-type printed wiring board made of glass epoxy resin; and

a step of forming an insulating layer after said step of forming a terminal portion in manufacturing said circuit board, said step of forming an insulating layer being to form an insulating layer in the other area than the area where said terminal portion is formed,

wherein said insulating layer is formed so as to cover a peripheral edge of said plated layer so that the surface of said circuit board and at least one of the surface of the base layer are not exposed externally, and the insulating layer is made of epoxy resin.

Claim 5 (Cancelled).

Claim 6 (Cancelled).

Claim 7 (Previously Presented): A method of manufacturing a battery pack according to claim 4, further comprising the steps of:

forming a base layer of a copper pattern on a surface of an insulating board;

forming a plated layer so as to cover the entire base layer by selective plating; and

forming an insulating layer on said plated layer and patterning said insulating layer so that only a portion of said plated layer is exposed externally.

Claims 8-10 (Cancelled).